



## Electrical and Optical Characteristics (Ta = 25°C)

Product Name	Typ. Emission Wavelength				Luminous Intensity I <sub>V</sub>			Forward Voltage V <sub>F</sub>			Reverse Current I <sub>R</sub>	
	λ <sub>d</sub>	λ <sub>p</sub>	Δλ	I <sub>F</sub>	Min	Typ.	I <sub>F</sub>	Typ.	Max	I <sub>F</sub>	Max	V <sub>R</sub>
TLRME68TG(F)	626	636	23	20	85	330	20	1.9	2.4	20	50	4
TLYE68TG(F)	587	590	17	20	85	340	20	2.0	2.4	20	50	4
TLGE68TG(F)	571	574	17	20	47.6	155	20	2.0	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

## Precautions

- These LED lamps made of InGaAlP will also emit some IR light. If a photodetector is located near an LED lamp, please ensure that it will not be affected by this IR light.
- Manual soldering should be performed within 3 s at a maximum temperature of 300°C or 5 s at a maximum temperature of 260°C.
- When forming the leads, bend each lead without applying any forming stress. Soldering must be performed after the leads have been formed.

## Mounting Precautions Using an Automatic Insertion Machine

- (1) These newly designed LED lamps are intended for mounting on both through-hole PCBs by means of an automatic mounting machine. Compared to conventional φ3-mm LED lamps, they are less prone to the effects of stress during automatic mounting (such as mechanical stress within the package resin transmitted via the leads). This reduced mechanical stress results in a lower incidence of damage to the package resin and lower emission failure rates. If one of these lamps is subjected to excessive stress, however, the resin part may break or the lamp may be damaged in such a way that it will not emit light.

Please take the following precautions when mounting these devices.

- Toshiba recommends the use of a 0.9-mm PCB hole diameter. However, this recommendation is subject to the type of automatic mounting machine used, the board material and the way in which the board material has been processed. Please evaluate the mounting process carefully before actually using the automatic mounting machine to mount these LED lamps. The use of PCB holes with a diameter larger than 0.9 mm may result in increased stress when soldering is performed (depending on the lead cutting shape and the clinching method), and devices may easily be malfunction.
- The insertion pressure and clinching angle must both be minimized so as to minimize the lead-cutting stress and clinch stress applied to the LED lamps.
- Soldering Conditions

	Preheating	Soldering Flow
Temperature	120 to 150°C	No more than 260°C
Time	Within 60 seconds	Within 5 seconds

- (2) Precautions when using Panasert radial-Taping automatic mounting machine:

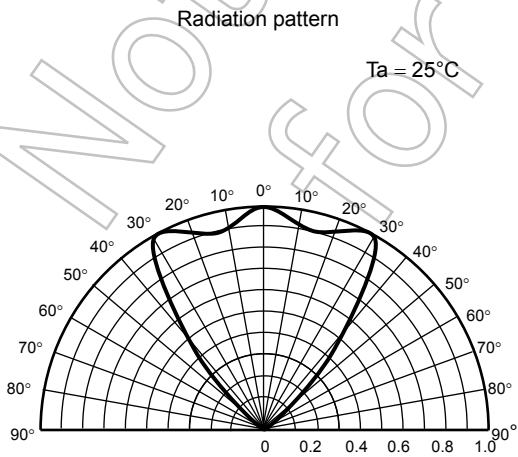
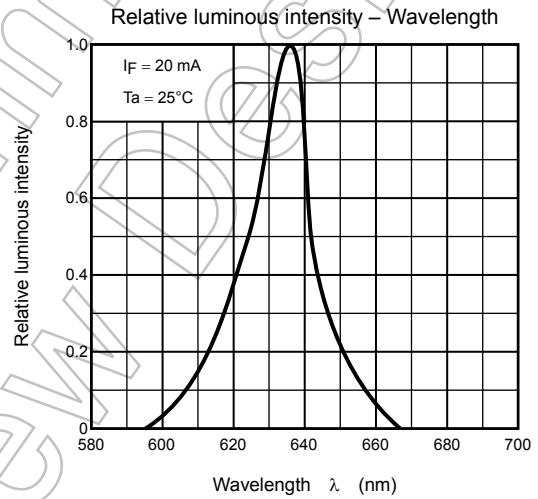
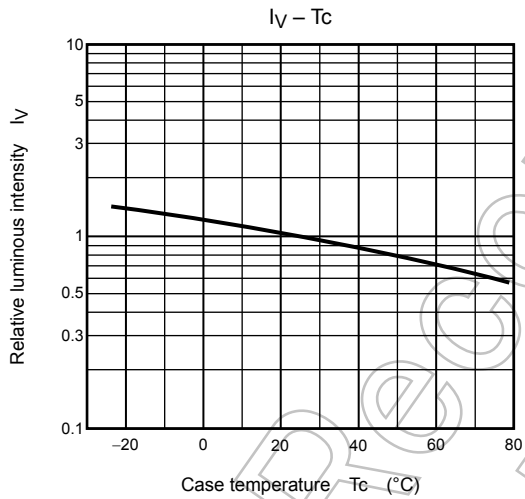
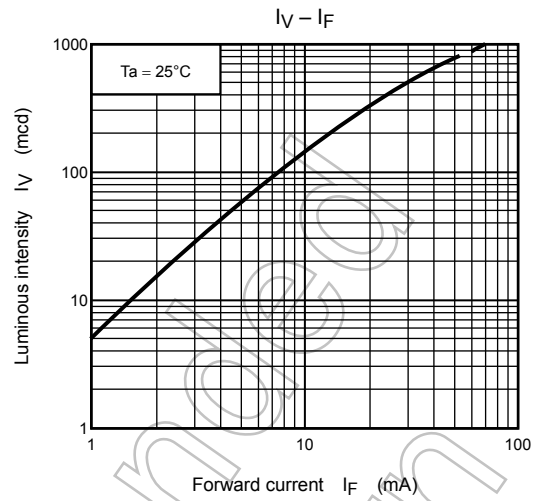
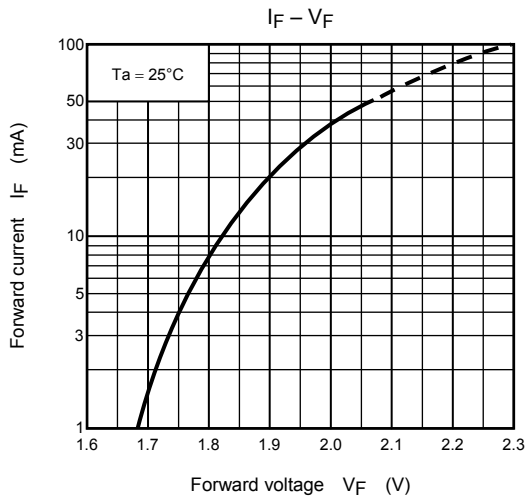
Two-lead LED lamps are suitable for mounting using an anvil due to its movable-blade structure.

When using three-lead type, please take the following precautions.

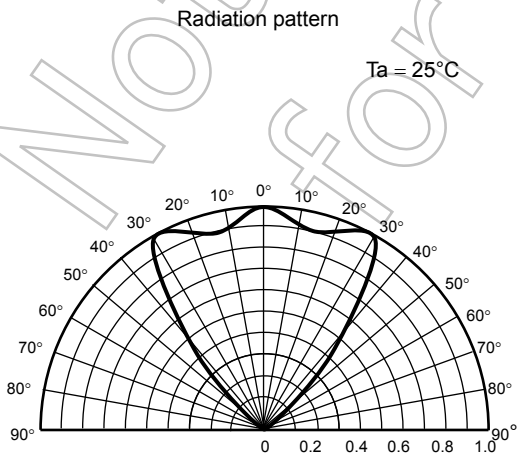
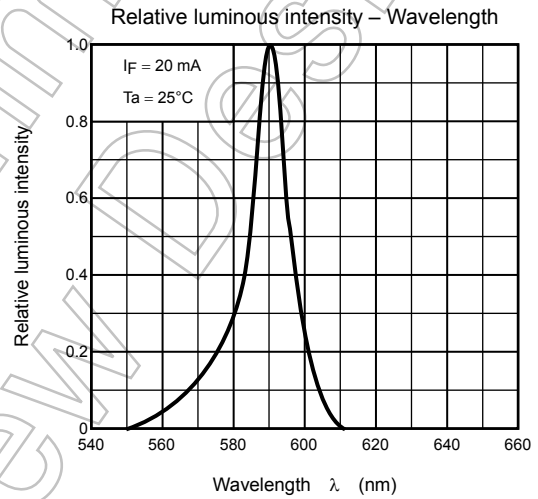
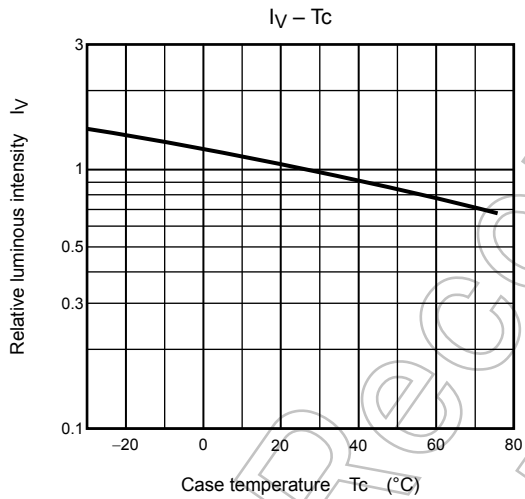
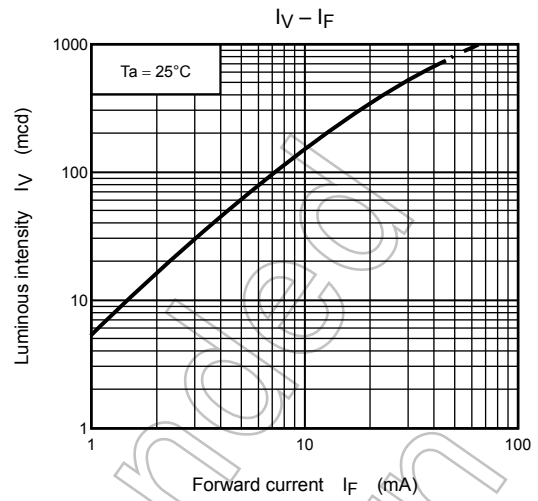
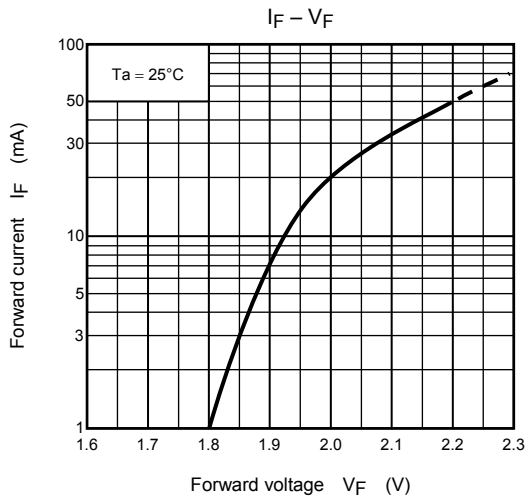
- Synchronize the strokes of the two movable blades to one another as closely as possible.
- Adjust the timings of the movable blades so as to minimize the difference between them. In addition, do not set the anvil in such a way that the anvil's center blade will pull the leads, as this will result in excessive mechanical stress to the LED lamps, which might damage them.
- Avoid any blade which is defective or which shows signs of excessive wear.

\* For using other than Panasert, please refer to the specifications for the automatic mounting machine which is to be used.

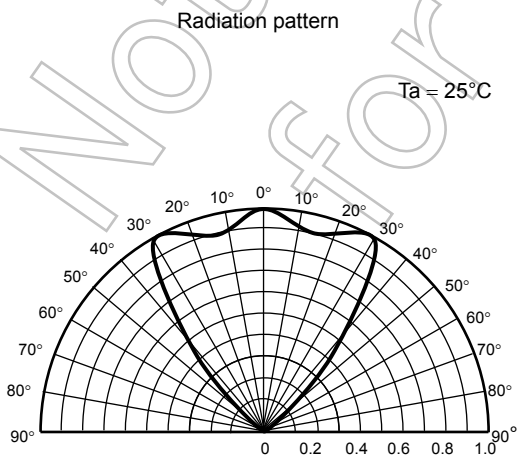
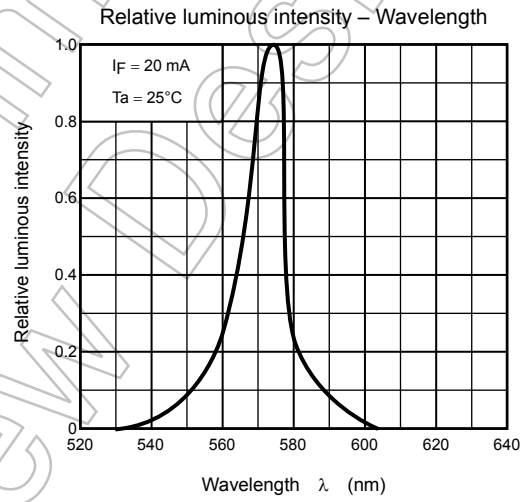
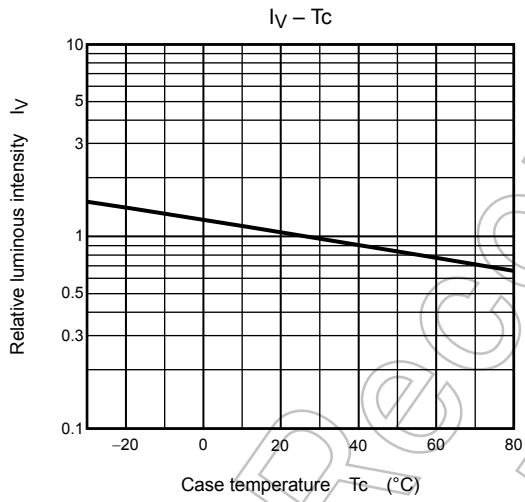
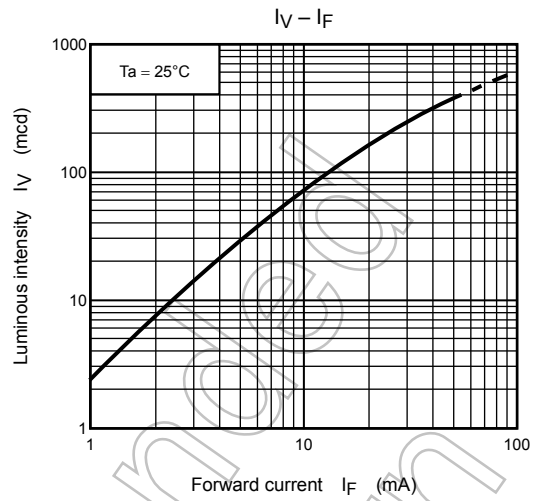
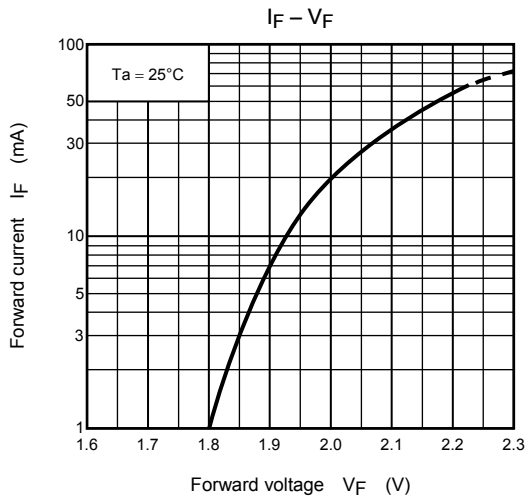
**TLRME68TG(F)**



**TLYE68TG(F)**



**TLGE68TG(F)**



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